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Michail Moroz - Publications List -

IMAPS SoCal'15 Technical Symposium Santa Ana, CA, May 12, 2015. 2005.
Ruthenium-based Resistors Fired at 680 C on Crystallizing Glass Substrates In:

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Affective and cognitive processes form a rich substrate on which learning Found in Proceedings of the 40th ACM technical symposium on Computer science education

Future and technical considerations of gold -

2.1 Cu wirebonding. Cu wirebonding has been hailed as is the primary alternate wirebonding option adopted over Au wirebonding in semiconductor packaging.

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granular and epitaxial superconducting thin films: NTRS Full-Text SrTiO₃ substrates were employed for Technical Symposium on Optical Engineering and

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2007) MEPTEC, the MicroElectronics Packaging and Test Engineering Council, Substrates: The Foundation of Semiconductor Packaging, at the Holiday Inn

COLLEGE OF ENGINEERING - Georgia Institute of Technology -

School of Electrical and Computer Engineering. Georgia Institute of Technology. Atlanta, GA 30332 Thin-Film Piezoelectric-on-Substrate Resonators and Narrowband

Limuel Balana | LinkedIn -

View Limuel Balana's professional profile on - Key technical contributor to the development of two metal layer substrate, (Phil) Technical Symposium,

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and a valuable learning tool for students by laying the groundwork for a solid foundation in the test area' for multidisciplinary technical and will

Professor Kenneth Grattan FEng | City University -

the UK National Academy of Engineering, in 2008. Professor Grattan has been Grattan, K.T. (Apr 2011). Technical Nov 2007). New test method to

SID Symposium Digest of Technical Papers -

Jul 28, 2015 10.1: Invited Paper: Roll-to-Roll Manufacturing of Functional Substrates and Encapsulation Films for Organic Electronics: Technologies and Challenges

MEPTEC Finalizes Program for Substrates Symposium -

(October 25, 2007) MEPTEC, the MicroElectronics Packaging and Test Engineering Council, has finalized the program for its upcoming technical symposium titled

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High temperature superconducting thin film microwave circuits: Fabrication, characterization, and microwave substrates. Technical Symposium on Optical

List of publications of an organisation - TU -

Platform for computational science and engineering symposium: The 10th Technical Symposium of the 15th European Microelectronics and Packaging Conference

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Program - Symposium SS: Bioelectronics Materials, -

Symposium SS: Bioelectronics Materials, Interfaces, and Applications is a technical symposium from the 2013 MRS Spring Meeting. This symposium will cover the

Characterization of imperfections in thin-film -

Characterization of imperfections in thin-film Presented at the 32nd International Technical Symposium on Optical and Opto Neutrons, Spectrometers, Substrates:

Technical Symposium on Packaging Developments and -

Technical Symposium on Packaging Developments and Innovations: From System Design Substrate Requirements and Options for 4th Generation Flip Chip Packages

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i PREFACE In the present day dynamic world, the importance of trans-disciplinary research in which the summation of knowledge gained by joint collaborative work

Seventh International Coatings for Plastics -

With over 20 technical papers presented, the Symposium focused on leading-edge issues in the coatings for plastics arena.

Electrochemical Impedance Spectroscopy of Bis -

Electrochemical Impedance Spectroscopy of Bis- 8-9 These studies have suggested that silane films connect to metal substrates by forming strong

Ramprakash Yerramilli, Faculty of Engineering, -

Faculty of Engineering. Photoelectrochemical studies on spray pyrolysed CdS films on SnO₂ substrates, Proc. 29th Annual International Technical Symposium on

Bibliographic list of staff publications, AGH -

Bibliographic list of staff publications, nuclear science symposium ; Technology conference and 34th international microelectronics and packaging :

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SPECIAL

Wood Coatings & Substrate Symposium - PCI Mag -

Wood Coatings & Substrate Symposium. July 29, 2012. KEYWORDS
symposium / wood coatings. Reprints. No Comments

The Taiwan Bookstore -

19th Annual International Symposium of the International Council on Systems
Engineering Technical Symposium of Test Integration and Packaging

ChipDesign Mag -

DesignVision Winners Take the Stage at DesignCon 2007 International
Engineering Consortium Semiconductor Test Consortium Manchester Technical
Symposium:

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Engineering Foundation Conference on Fluidization